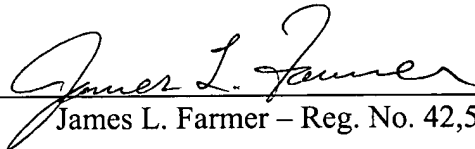


Should the Examiner wish to discuss the above in greater detail, then the Examiner is invited to telephone the undersigned at the Examiner's convenience.

Respectfully submitted,

Date: August 30, 2001

By 
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MARKED-UP VERSION

In the Specification

On page 1, under the heading “Cross-References to Related Applications”, the paragraph directly below beginning on line 10:

This application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee.

On page 10, the first full paragraph beginning on line 9:

While the preferred embodiment of the invention has been illustrated and described, it will be appreciated that various changes can be made therein without departing from the spirit and scope of the invention. For example, the buff pad may include grooves or slurry holes. Further, the present invention may be applied to other, more primary, processes in which a rotating head is pressed to a circular wafer for the purpose of removing portions of the wafer surface. In this regard, the term “buff” pad and “buffing” as used herein are generically defined to mean a material removing article [including] excluding a primary polish step.